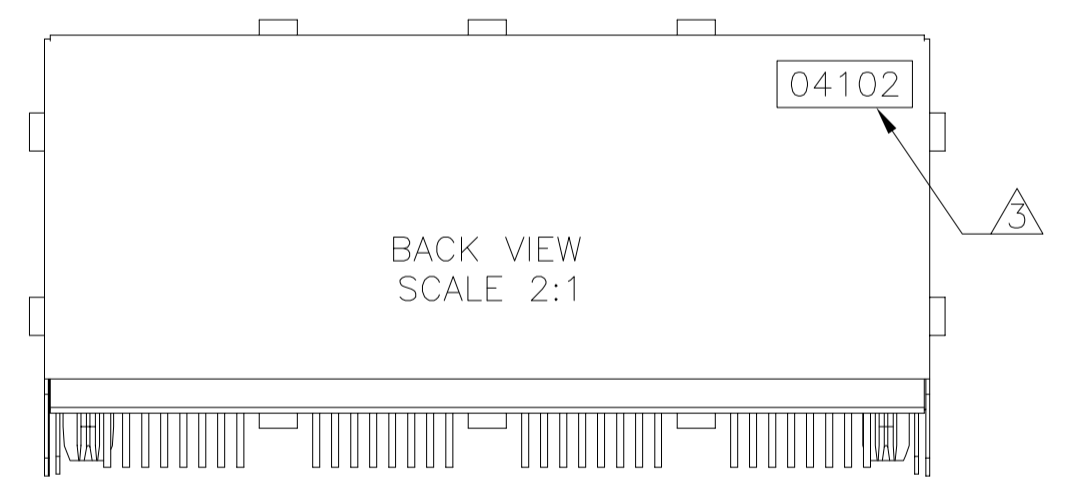
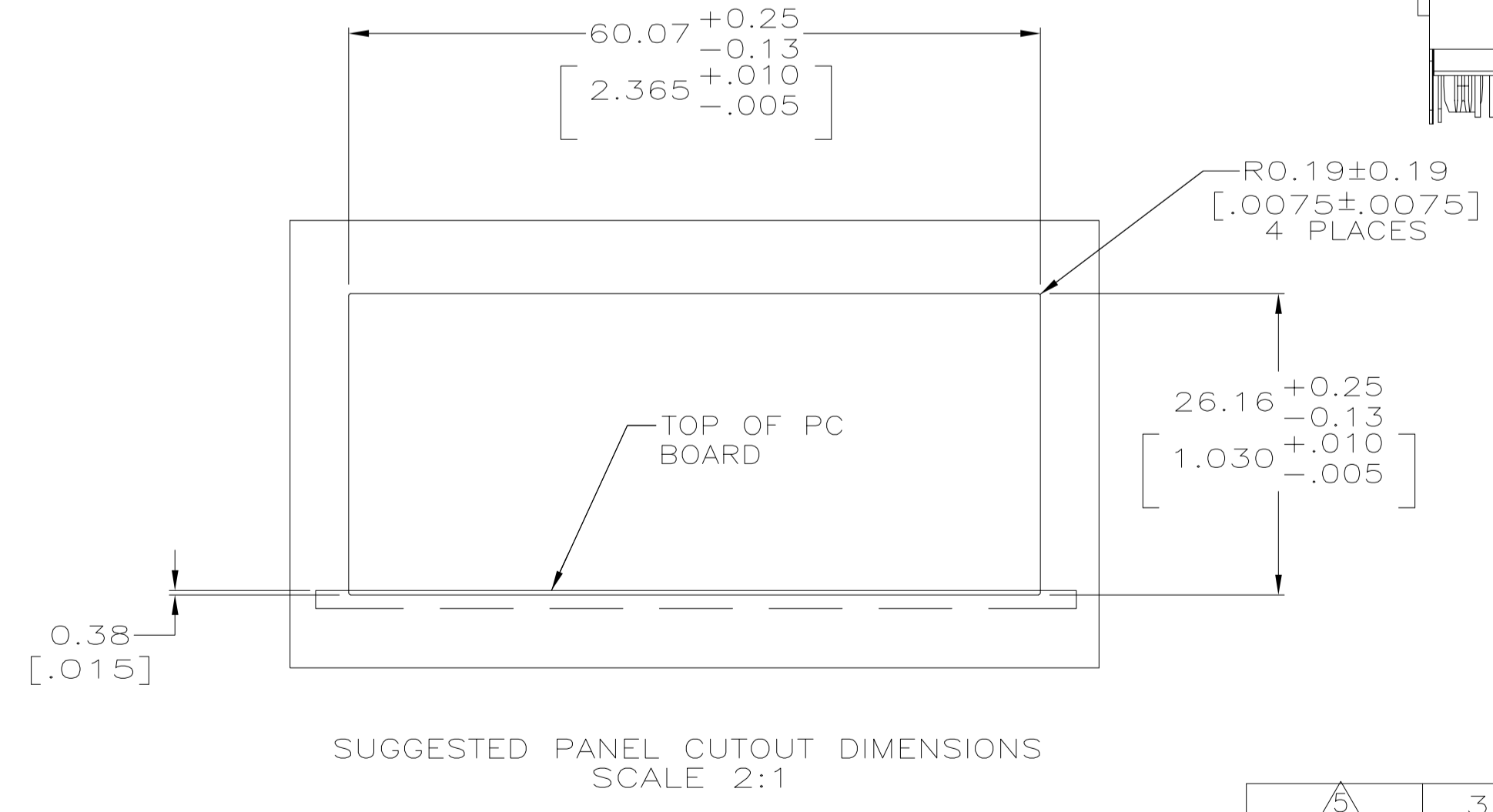
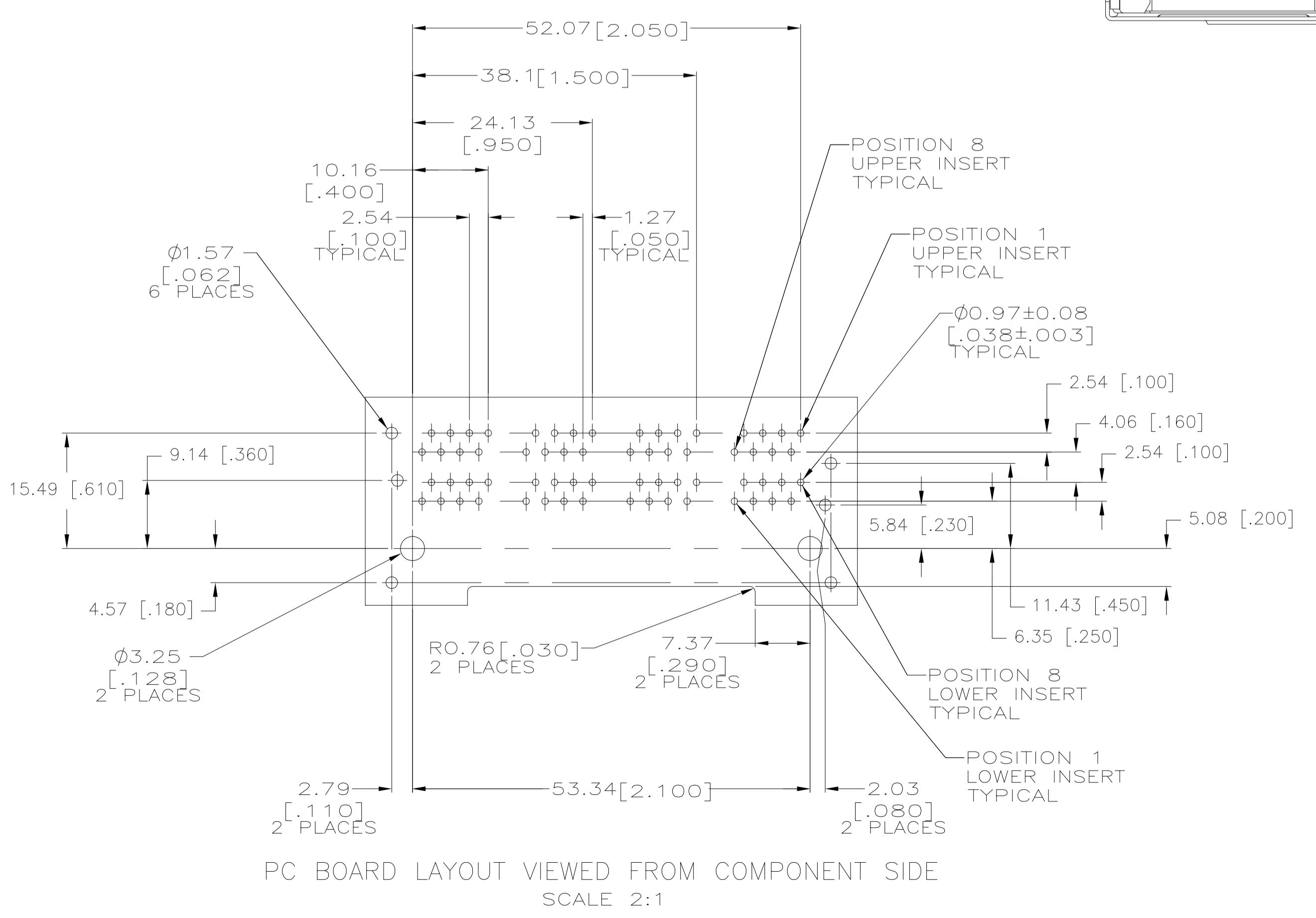
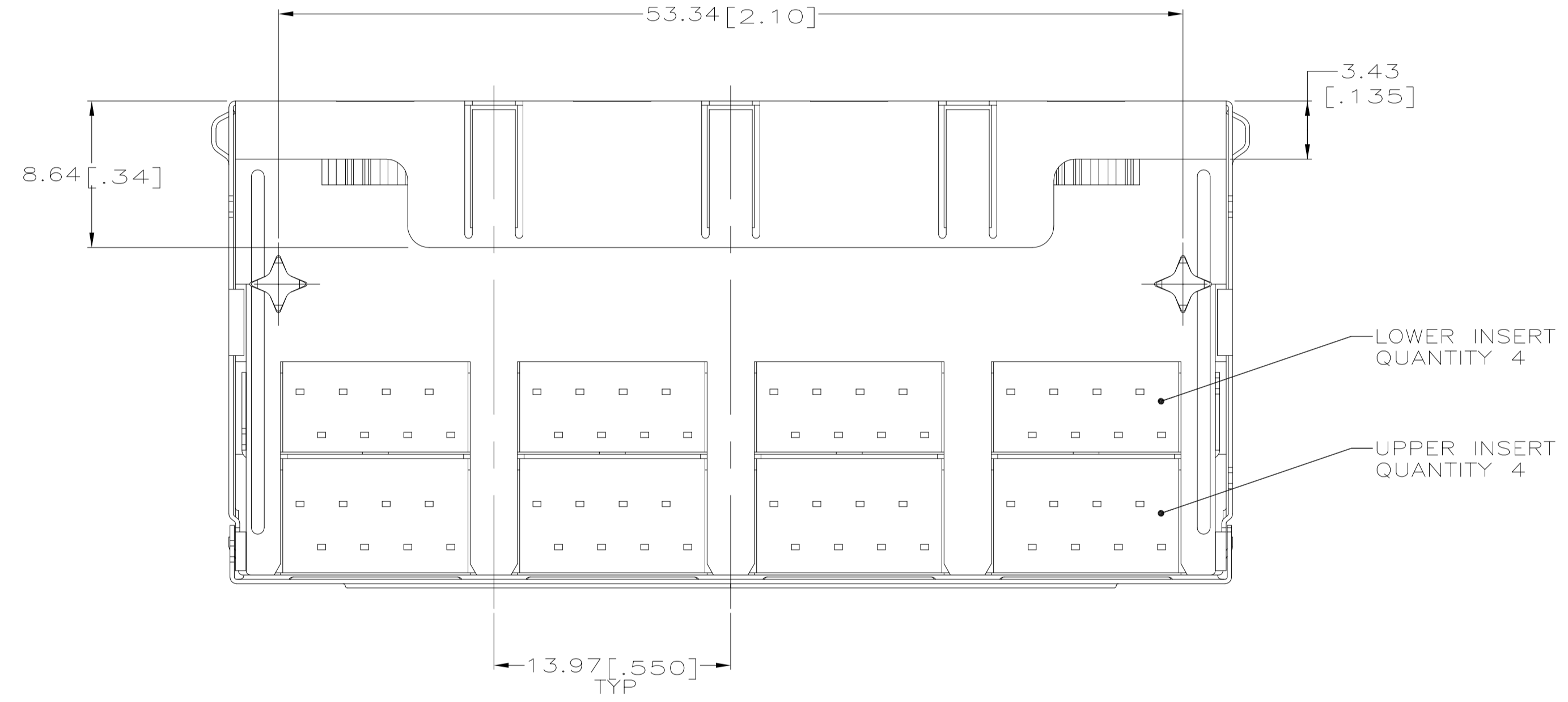
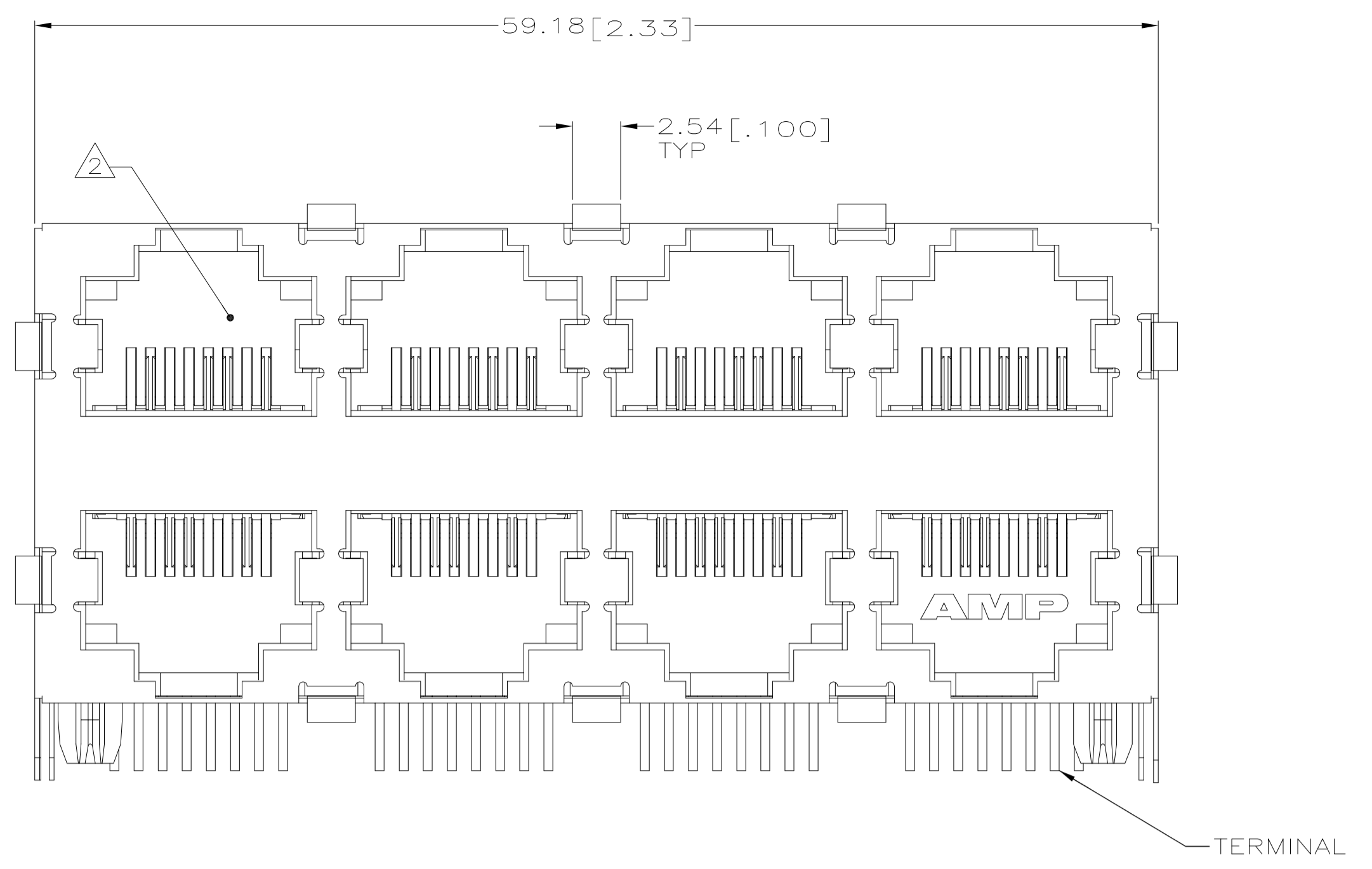
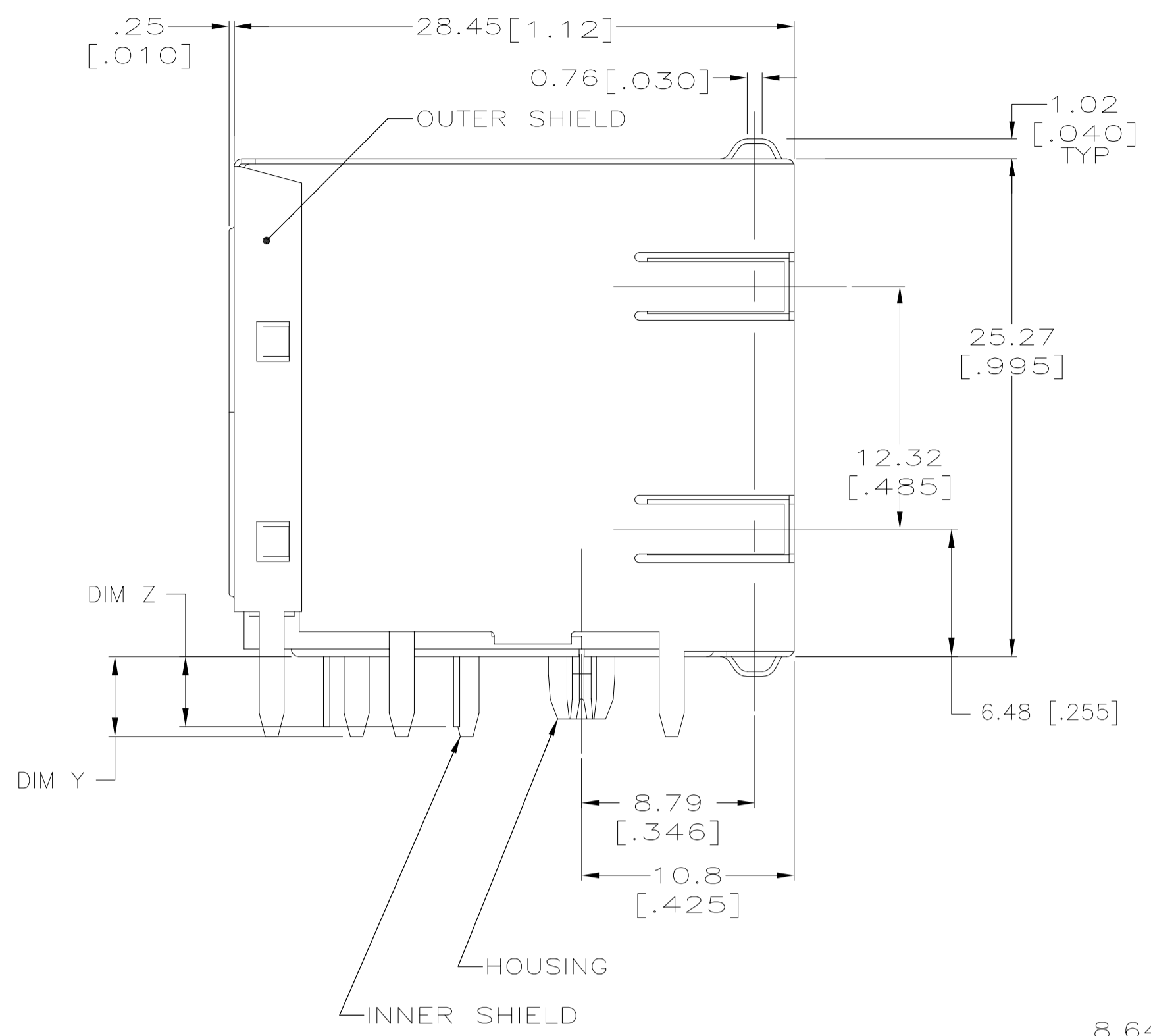


LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APP'D
B3		REVISED PER ECO-15-011392	06AUG2015	LL	SH



- MATERIAL: HOUSING - PCT POLYESTER, BLACK, UL94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33 [.013] THICK PHOS BRONZE PLATED WITH 1.27um [.000050] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81um [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27um [.000050] MIN THICK NICKEL UNDERPLATE. SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 2.03um [.000080] MIN BRIGHT TIN OVER 1.27um [.000050] MIN NICKEL.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN: FIRST 2 DIGITS ARE LAST 2 DIGITS OF YEAR, SECOND 2 DIGITS ARE MANUFACTURING WORK WEEK, LAST DIGIT IS DAY OF WEEK, WITH SUNDAY = 1.
- MATERIAL: HOUSING - PCT POLYESTER, BLACK, UL94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33 [.013] THICK PHOS BRONZE PLATED WITH 1.27um [.000050] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81um [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27um [.000050] MIN THICK NICKEL UNDERPLATE. SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- MATERIAL: HOUSING - PCT POLYESTER, BLACK, UL94V-0. OVERMOLDED TERMINAL ARRAY - PBT, BROWN. TERMINALS - 0.33 [.013] THICK PHOS BRONZE PLATED WITH 0.381um [.000015] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81um [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27um [.000050] MIN THICK NICKEL UNDERPLATE. SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

REMARK	DIM. Z	DIM. Y	PART NUMBER
5	3.56 [.140]	4.06 [.160]	5569262-2
3	3.05 [.120]	4.06 [.160]	1-5569262-1
4	3.56 [.140]	4.06 [.160]	5569262-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN: T. SPRINKLE/LA MAYER, J. WESTMAN

APVD: S. FLICKINGER

PRODUCT SPEC: 108-1163-2

APPLICATION SPEC: 114-2048

WEIGHT: -

CUSTOMER DRAWING

SCALE: 4:1

SHEET: 1 OF 1

REV: B3

STE TE Connectivity

STACKED MODULAR JACK ASSEMBLY, 2x4 PORT, 8 POSITION, SHIELDED, PANEL GROUND, CATEGORY 5

# Mouser Electronics

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[TE Connectivity:](#)

[1-5569262-1](#)